

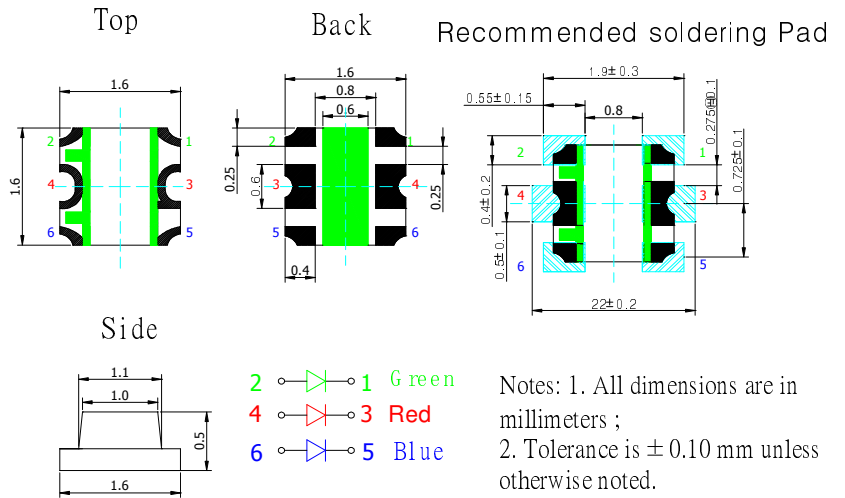
■Features

- Full-Color
- Super high brightness of surface mount LED
- Water Clear Flat Mold
- Compact package outline
(LxWxT) of 1.6mm x 1.6mm x 0.5mm
- Compatible to IR reflow soldering.

■Applications

- Backlighting (switches, keys, etc.)
- Marker lights (e.g. steps, exit ways, etc.)

■Outline Dimension



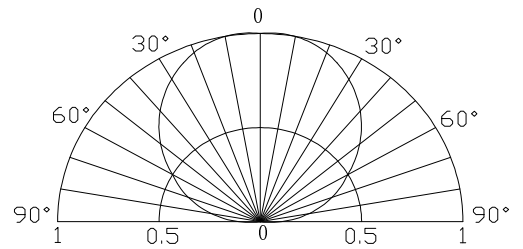
■Absolute Maximum Rating

(Ta=25°C)

Item	Symbol	Value		Unit
		HR	PG/BL	
DC Forward Current	I _F	25	25	mA
Pulse Forward Current*	I _{FP}	100	100	mA
Reverse Voltage	V _R	5	5	V
Power Dissipation	P _D	65	90	mW
Operating Temperature	T _{opr}	-40 ~ +85		°C
Storage Temperature	T _{stg}	-40 ~ +85		°C
Lead Soldering Temperature	T _{sol}	260°C/10sec		-

*Pulse width Max 0.1ms, Duty ratio max 1/10

■Directivity



■Electrical -Optical Characteristics

(Ta=25°C)

Part Number	Color		V _F (V)			I _R (μA)	I _v (mcd)			λ _D (nm)			2θ1/2(deg)
			Min.	Typ.	Max.	Max.	Min.	Typ.	Max.	Min.	Typ.	Max.	Typ.
			I _F =20mA			V _R =5V	I _F =20mA						
OSTF1616C1C	Blue	BL	2.8	3.0	3.6	10	50	80	-	465	470	475	120
	Pure Green	PG	2.8	3.0	3.6	10	450	600	-	520	525	530	120
	Red	HR	1.8	2.0	2.6	10	180	250	-	617	625	630	120

*1 Tolerance of measurements of dominant wavelength is ±1nm

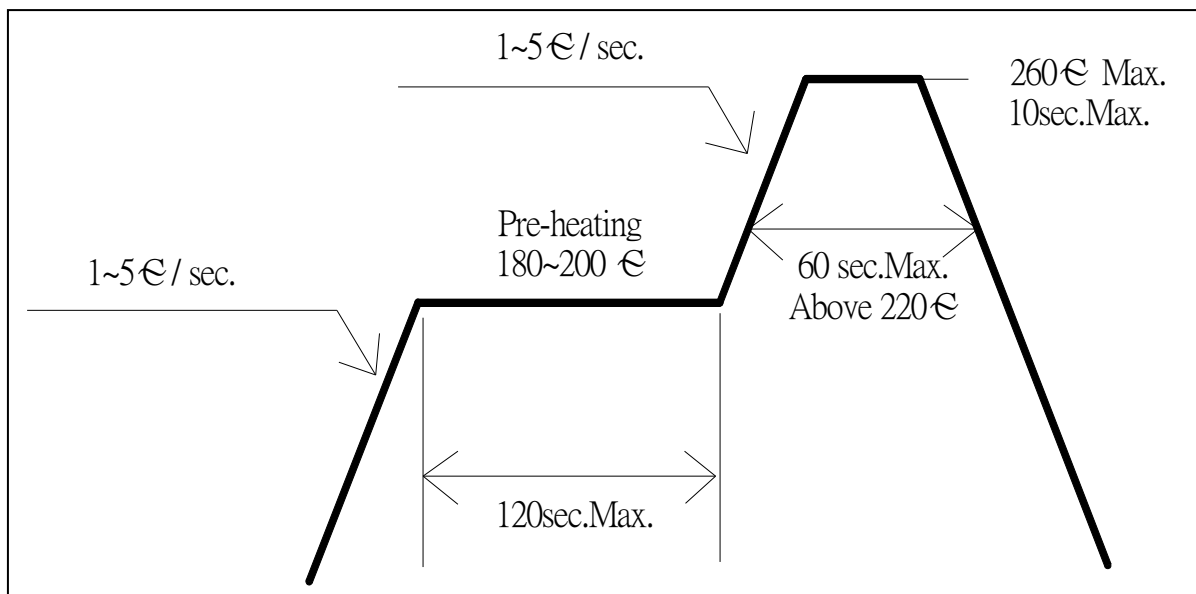
*2 Tolerance of measurements of luminous intensity is ±15%

*3 Tolerance of measurements of forward voltage is ±0.1V

■ Soldering Conditions

Reflow Soldering		Hand Soldering	
Pre-Heat	180 ~ 200°C	Temperature Soldering time	350°C Max. 3 sec. Max. (one time only)
Pre-Heat Time	120 sec. Max.		
Peak temperature	260°C Max.		
Dipping Time	10 sec. Max.		
Condition	Refer to Temperature-profile		

• Reflow Soldering Condition(Lead-free Solder)



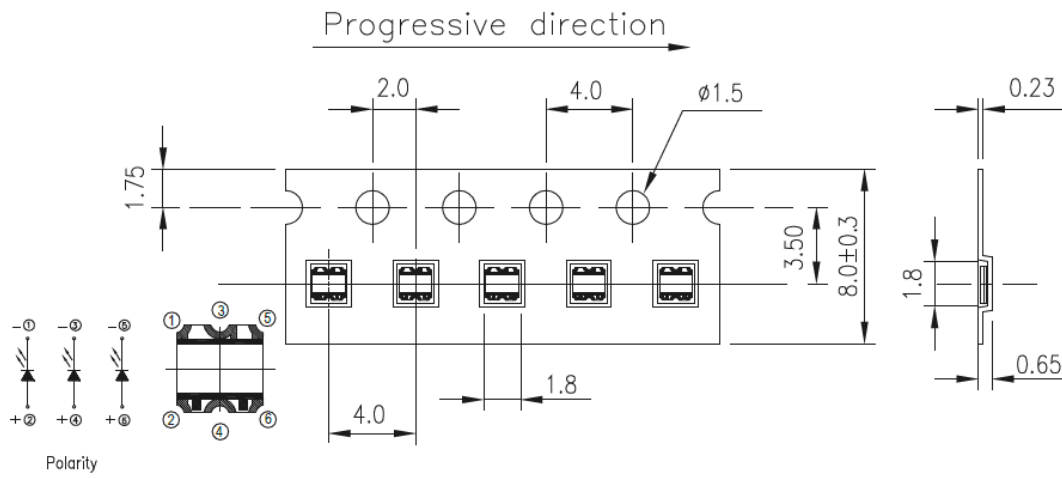
*Recommended soldering conditions vary according to the type of LED

*Although the recommended soldering conditions are specified in the above table, reflow, or hand soldering at the lowest possible temperature is desirable for the LEDs.

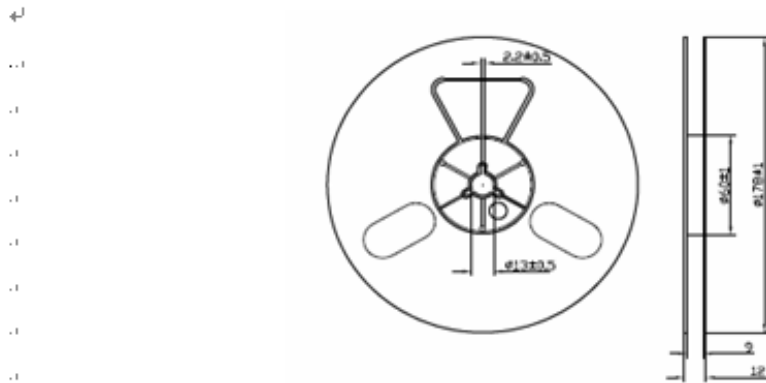
*A rapid-rate process is not recommended for cooling the LEDs down from the peak temperature.

- All SMD LED products are pb-free soldering available.
- Occasionally there is a brightness decrease caused by the influence of heat or ambient atmosphere during air reflow. It is recommended that the User use the nitrogen reflow method.
- Repairing should not be done after the LEDs have been soldered. When repairing is unavoidable a double-head soldering iron should be used. It should be confirmed beforehand whether the characteristics of the LEDs will or will not be damaged by repairing.
- Reflow soldering should not be done more than two times.
- When soldering, do not put stress on the LEDs during heating.
- After soldering, do not warp the circuit board.

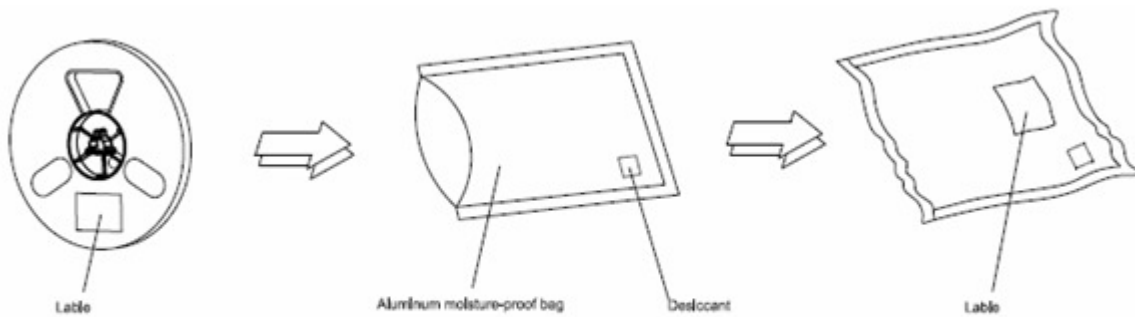
■ Reel & Tape Dimensions (2000pcs/reel) :



Reel Dimensions ↴



Moisture Resistant Packaging ↴



Note: The tolerances unless mentioned is ± 0.1 mm, Unit: mm